

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jlang et al.

Art Unit: 1765

Serial No.: 09/966,605

Examiner: Vinh, Lan

Filing Date: 09/28/2001

Docket No.: TI-31462

Customer No.: 23494

Conf. No.: 4769

Title: IN-SITU PLASMA ASH/TREATMENT AFTER VIA ETCH OF LOW-K
FILMS FOR POISON-FREE DUAL DAMASCENE TRENCH PATTERNING**REQUEST FOR EXTENSION OF TIME**Commissioner of Patents
PO Box 1450
Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATION OF FACSIMILE TRANSMISSIONI hereby certify that the following papers are being transmitted by
facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on
the date shown below:

Jacqueline J. Garner, Reg. No. 36,144

April 19, 2004
Date

Pursuant to 37 CFR 1.136(a), Applicant(s) respectfully petitions the Commissioner
for an extension of the shortened statutory period for response in the above-identified
Application.

The fee for this extension is indicated below:

☐ One Month (\$110)☒ Two Months (\$420)☐ Three Months (\$950)☐ Four Months (\$1,480)

Please charge the fee to deposit account no. 20-0668. Any further necessary
extension of time is hereby requested. Charge any and all fees to deposit account no. 20-
0668. An original and two copies of this sheet are enclosed.

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Respectfully Submitted,

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